

AFE77xx PG2.0 SMT process is same as AFE77xx PG1.1

Ball/column alloy element)	SAC305
Ball/column phosphorus element	≤2ppm
Interconnect between die and substrate	Flip chip with lead-free bump
BGA substrate finish	OSP
Package standard	JEDEC
Weight (g)	2.074g
Flatness of the pick area	≤0.1mm
Lead/leadless/solder ball co-planarity	150 um (Ref. POD)
Is there any Pin 1 Mark point in the top side of component?	Yes
Is the Pin 1 mark point sole?	Yes
Is there any specific location number of terminals in the component specification?	Yes
Package Warpage meet requirement	Yes
Are matters RoHS compliant listed below?	Yes
Storage: Relative humidity (%)	20%≤RH≤70%
Storage Temperature (°C)	–55°C to +150°C
Maximum storage time for the component (month)	24
Storage time for the packing satisfy the component maximum storage time (MSL 3)	yes
packaging standard	JEDEC
Packaging type	TRAY
Position of component pin 1 in packing	Pin 1 placed at the tray chamfered corner
Packaging height H	H: 7.62 mm
Packaging width W	W: 136 mm (LxWxH=322.6mm x 136mm x 7.62mm)
Packaging satisfy ASTM F1249 standards	YES
Vacuum and moisture-proof packing	YES
Anti-sulfur packaging	YES
MSL	Level-3-260C
Baking Standards	J-STD-033
MSL added on the smallest packing	YES
Humidity indicator and drying agent separate in packing	YES
Humidity indicator and drying agent added in the smallest packing, and the humidity indicator must include RH5%, 10%, 60%. The color change from blue to pink	YES
Soldering method	Reflow
Maximum Reflow Soldering times	3 times
Can heat resistance of SMT components meet JSTD020D.	yes
solderability test	PASS